

CHIPLED

LG Q971, LY Q971



Besondere Merkmale

- **Gehäusotyp:** 0603
- **Besonderheit des Bauteils:** kleinste Bauform 1,6 mm x 0,8 mm x 0,8 mm
- **Wellenlänge:** 570 nm (grün), 590 nm (gelb)
- **Abstrahlwinkel:** extrem breite Abstrahlcharakteristik (160°)
- **Technologie:** GaP (grün), GaAsP (gelb)
- **optischer Wirkungsgrad:** 2,5 lm/W (grün), 1,5 lm/W (gelb)
- **Verarbeitungsmethode:** für alle SMT-Bestücktechniken geeignet
- **Lötmethode:** IR Reflow Löten
- **Vorbehandlung:** nach JEDEC Level 2
- **Gurtung:** 8 mm Gurt mit 4000/Rolle, ø180 mm

Anwendungen

- Informationsanzeigen im Innenbereich
- optischer Indikator
- Flache Hinterleuchtung (LCD, Handy, Schalter, Display)
- Spielsachen

Features

- **package:** 0603
- **feature of the device:** smallest package 1.6 mm x 0.8 mm x 0.8 mm
- **wavelength:** 570 nm (green), 590 nm (yellow)
- **viewing angle:** extremely wide (160°)
- **technology:** GaP (green), GaAsP (yellow)
- **optical efficiency:** 2.5 lm/W (green), 1.5 lm/W (yellow)
- **assembly methods:** suitable for all SMT assembly methods
- **soldering methods:** IR reflow soldering
- **preconditioning:** acc. to JEDEC Level 2
- **taping:** 8 mm tape with 4000/reel, ø180 mm

Applications

- indoor displays
- optical indicators
- flat backlighting (LCD, cellular phones, switches, displays)
- toys

Typ Type	Emissionsfarbe Color of Emission	Farbe der Lichtaustrittsfläche Color of the Light Emitting Area	Lichtstärke Luminous Intensity $I_F = 20 \text{ mA}$ $I_V \text{ (mcd)}$		Bestellnummer Ordering Code
			min.	typ.	
LG Q971	green	colorless diffused	7.1	10	Q62702-P5189
LY Q971	yellow	colorless diffused	2.8	6	Q62703-Q4699

Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 11 \%$ ermittelt.
Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of $\pm 11 \%$.

*Anm.: Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe, die aus nur 3 bzw. 4 Halbgruppen besteht. Einzelne Halbgruppen sind nicht erhältlich.
In einer Verpackungseinheit / Gurt ist immer nur eine Halbgruppe enthalten.*

*Note: The standard shipping format for serial types includes a lower or upper family group of 3 or 4 individual groups. Individual half groups are not available.
No packing unit / tape ever contains more than one luminous intensity half group.*

Grenzwerte
Maximum Ratings

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebstemperatur Operating temperature range	T_{op}	- 30 ... + 85	°C
Lagertemperatur Storage temperature range	T_{stg}	- 40 ... + 85	°C
Sperrschichttemperatur Junction temperature	T_j	+ 95	°C
Durchlassstrom Forward current	I_F	25 (green) 20 (yellow)	mA
Stoßstrom Surge current $t_p = 10 \mu s, D = 0.1$	I_{FM}	0.1	A
Sperrspannung Reverse voltage	V_R	5	V
Leistungsaufnahme Power consumption	P_{tot}	65	mW
Wärmewiderstand Thermal resistance Sperrschicht/Umgebung Junction/ambient	$R_{th JA}$	800	K/W
Sperrschicht/Löt看垫 Junction/solder point Montage auf PC-Board FR 4 (Padgröße $\geq 16 \text{ mm}^2$) mounted on PC board FR 4 (pad size $\geq 16 \text{ mm}^2$)	$R_{th JS}$	450	K/W

Kennwerte ($T_A = 25\text{ °C}$)
Characteristics

Bezeichnung Parameter	Symbol Symbol	Werte Values		Einheit Unit
		LG	LY	
Wellenlänge des emittierten Lichtes (typ.) Wavelength at peak emission $I_F = 20\text{ mA}$	λ_{peak}	572	589	nm
Dominantwellenlänge ¹⁾ (typ.) Dominant wavelength ¹⁾ $I_F = 20\text{ mA}$	λ_{dom}	570	590	nm
Spektrale Bandbreite (typ.) Spectral bandwidth $I_F = 20\text{ mA}$	$\Delta\lambda$	30	40	nm
Abstrahlwinkel bei 50 % I_V (Vollwinkel) (typ.) Viewing angle at 50 % I_V	2ϕ	160	160	Grad deg.
Durchlassspannung ²⁾ (typ.) Forward voltage ²⁾ (max.) $I_F = 20\text{ mA}$	V_F V_F	2.2 2.5	2.2 2.5	V V
Sperrstrom (typ.) Reverse current (max.) $V_R = 5\text{ V}$	I_R I_R	0.02 100	0.02 100	μA μA
Temperaturkoeffizient von λ_{peak} (typ.) Temperature coefficient of λ_{peak} $I_F = 20\text{ mA}; -10\text{ °C} \leq T \leq 100\text{ °C}$	$TC_{\lambda_{\text{peak}}}$	0.10	0.11	nm/K
Temperaturkoeffizient von λ_{dom} (typ.) Temperature coefficient of λ_{dom} $I_F = 20\text{ mA}; -10\text{ °C} \leq T \leq 100\text{ °C}$	$TC_{\lambda_{\text{dom}}}$	0.06	0.08	nm/K
Temperaturkoeffizient von V_F (typ.) Temperature coefficient of V_F $I_F = 20\text{ mA}; -10\text{ °C} \leq T \leq 100\text{ °C}$	TC_V	- 1.4	- 1.7	mV/K
Optischer Wirkungsgrad (typ.) Optical efficiency $I_F = 20\text{ mA}$	η_{opt}	2.5	1.5	lm/W

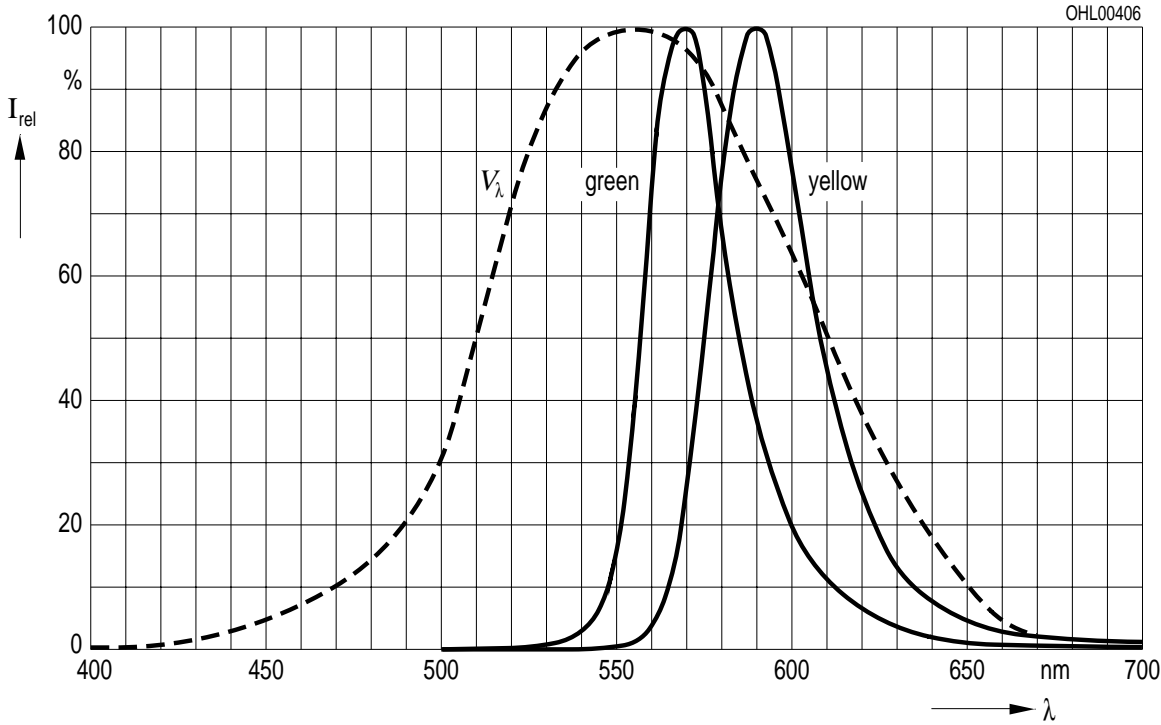
¹⁾ Wellenlängengruppen werden mit einer Stromeinprägungsdauer von 25 ms und einer Genauigkeit von $\pm 1\text{ nm}$ ermittelt.
Wavelength groups are tested at a current pulse duration of 25 ms and a tolerance of $\pm 1\text{ nm}$.

²⁾ Spannungswerte werden mit einer Stromeinprägungsdauer von 1 ms und einer Genauigkeit von $\pm 0,1\text{ V}$ ermittelt.
Voltages are tested at a current pulse duration of 1 ms and a tolerance of $\pm 0.1\text{ V}$.

Relative spektrale Emission $I_{rel} = f(\lambda)$, $T_A = 25\text{ °C}$, $I_F = 20\text{ mA}$

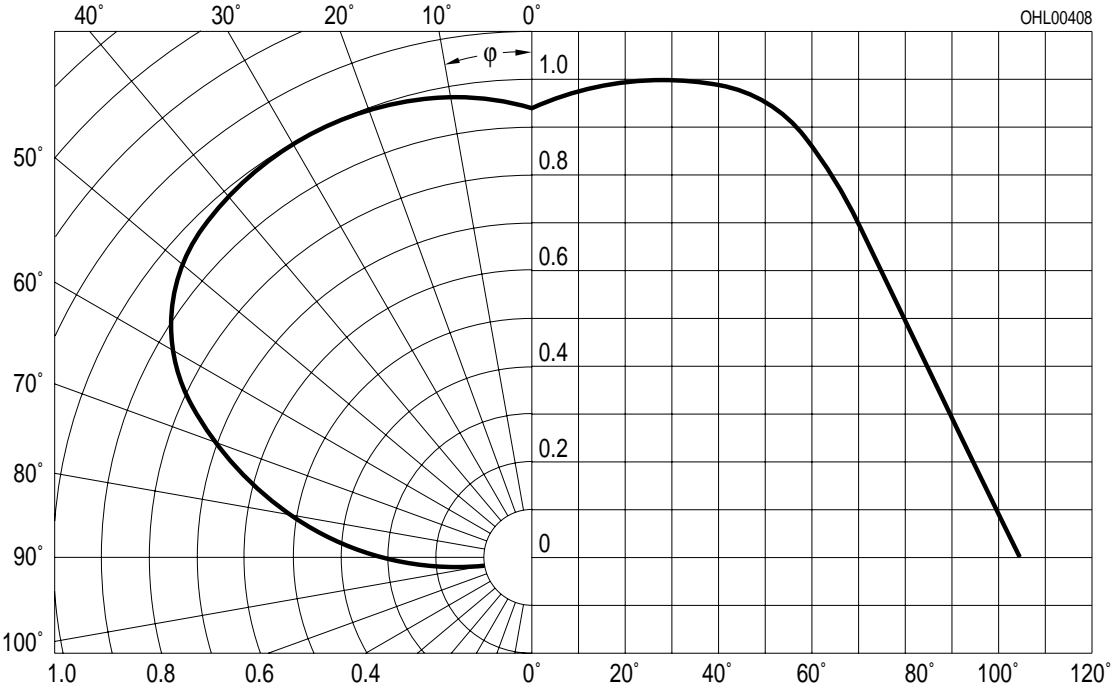
Relative Spectral Emission

$V(\lambda)$ = spektrale Augenempfindlichkeit
Standard eye response curve



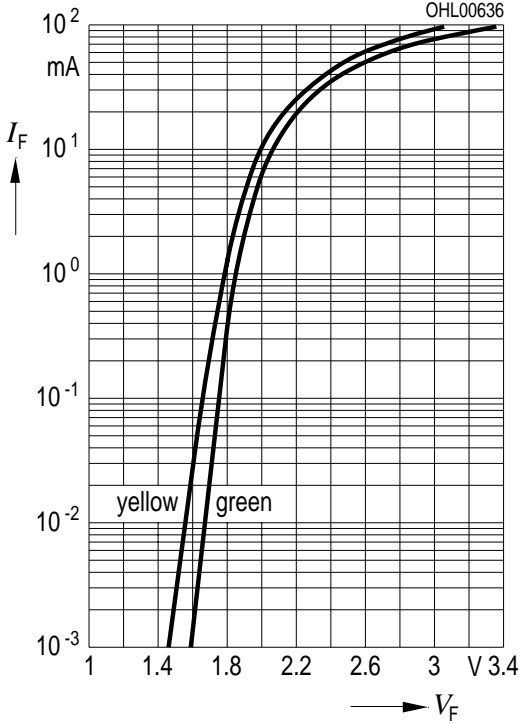
Abstrahlcharakteristik $I_{rel} = f(\varphi)$

Radiation Characteristic



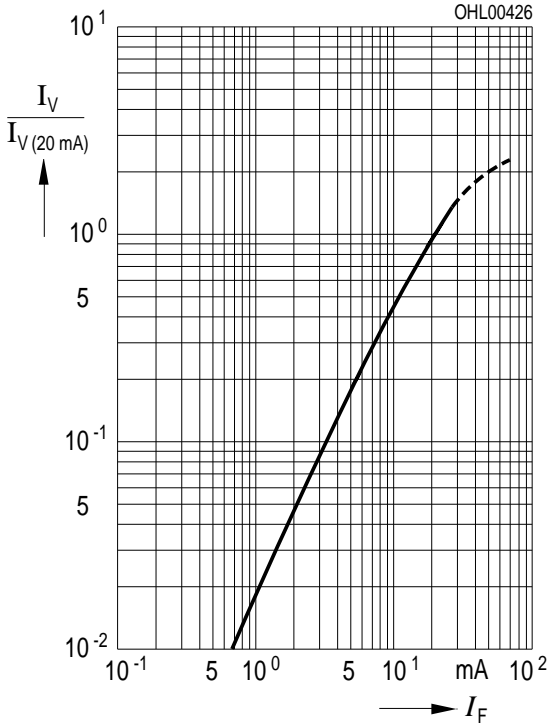
Durchlassstrom $I_F = f(V_F)$
Forward Current

$T_A = 25\text{ °C}$

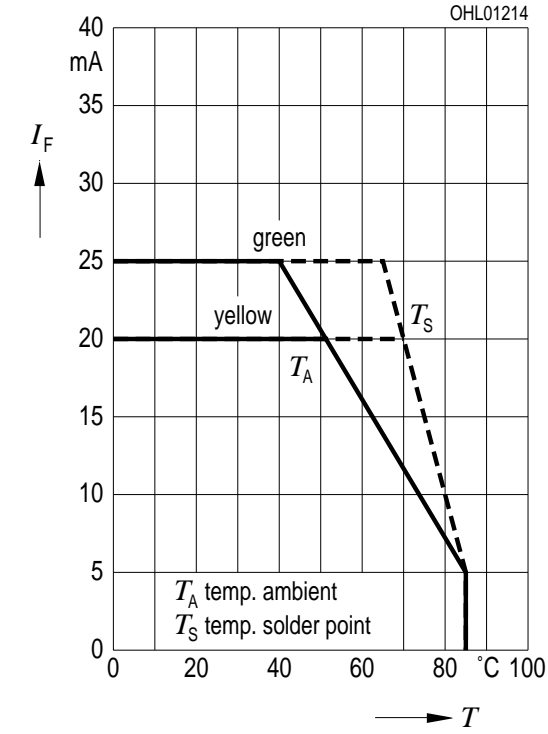


Relative Lichtstärke $I_V/I_{V(20\text{ mA})} = f(I_F)$
Relative Luminous Intensity

$T_A = 25\text{ °C}$

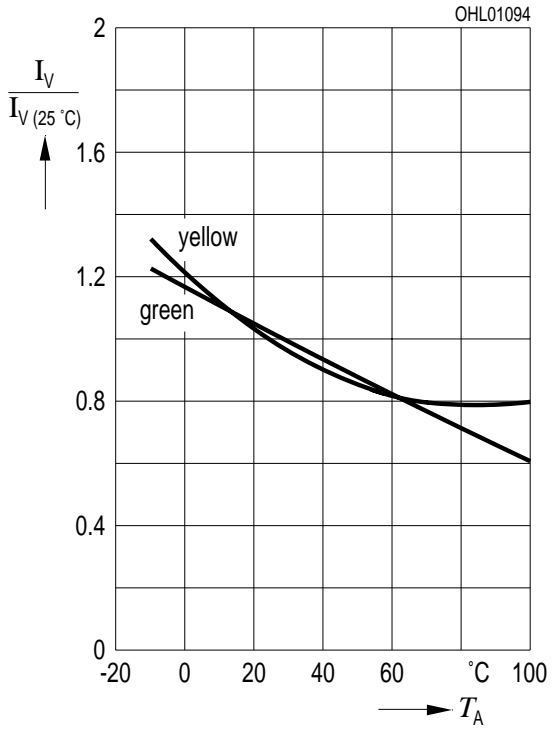


Maximal zulässiger Durchlassstrom $I_F = f(T_A)$
Max. Permissible Forward Current

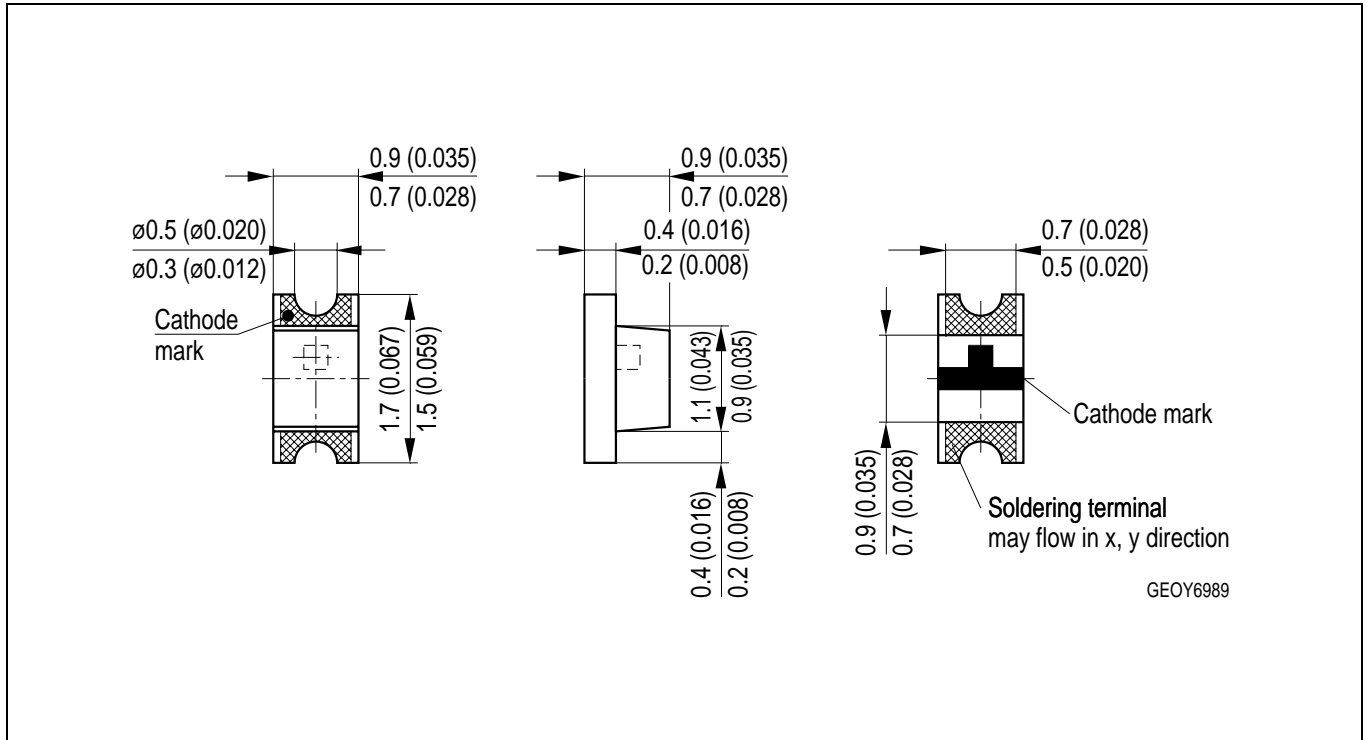


Relative Lichtstärke $I_V/I_{V(25\text{ °C})} = f(T_A)$
Relative Luminous Intensity

$I_F = 20\text{ mA}$



**Maßzeichnung
Package Outlines**

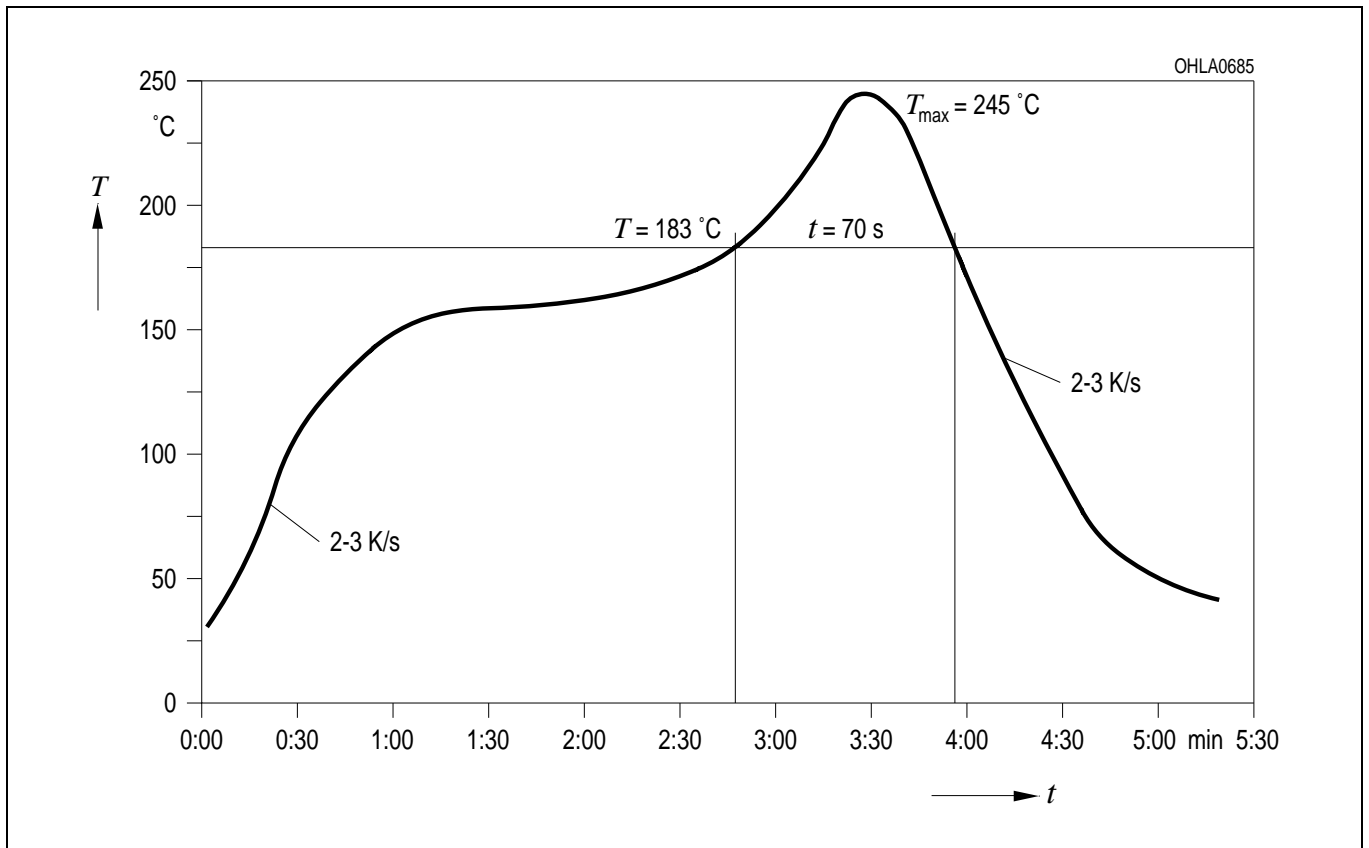


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

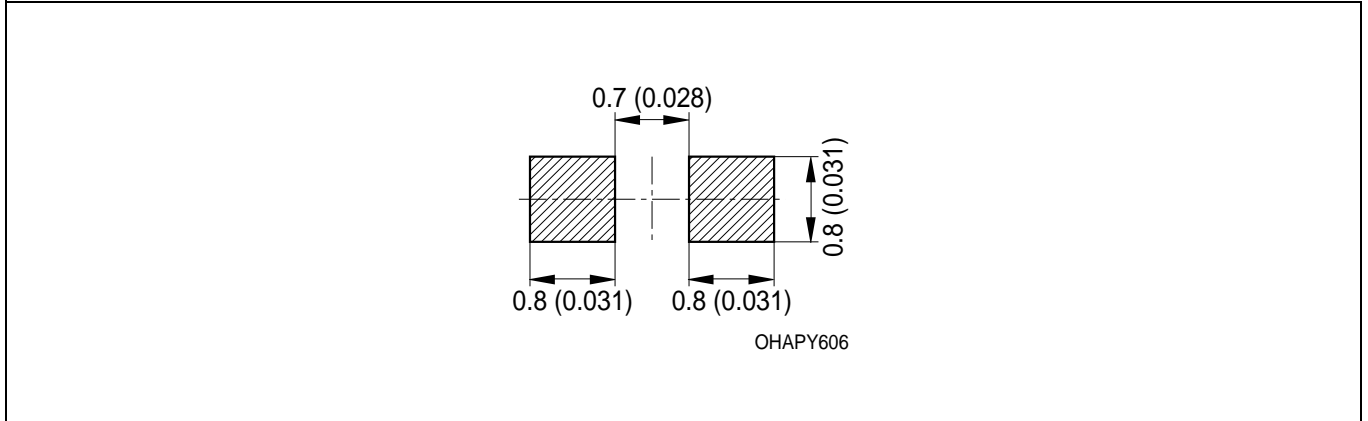
Gewicht / Approx. weight: 1.4 mg

Lötbedingungen Vorbehandlung nach JEDEC Level 2
Soldering Conditions Preconditioning acc. to JEDEC Level 2

IR-Reflow Lötprofil (nach IPC 9501)
IR Reflow Soldering Profile (acc. to IPC 9501)



Empfohlenes Lötpad design IR Reflow Löten
Recommended Solder Pad IR Reflow Soldering



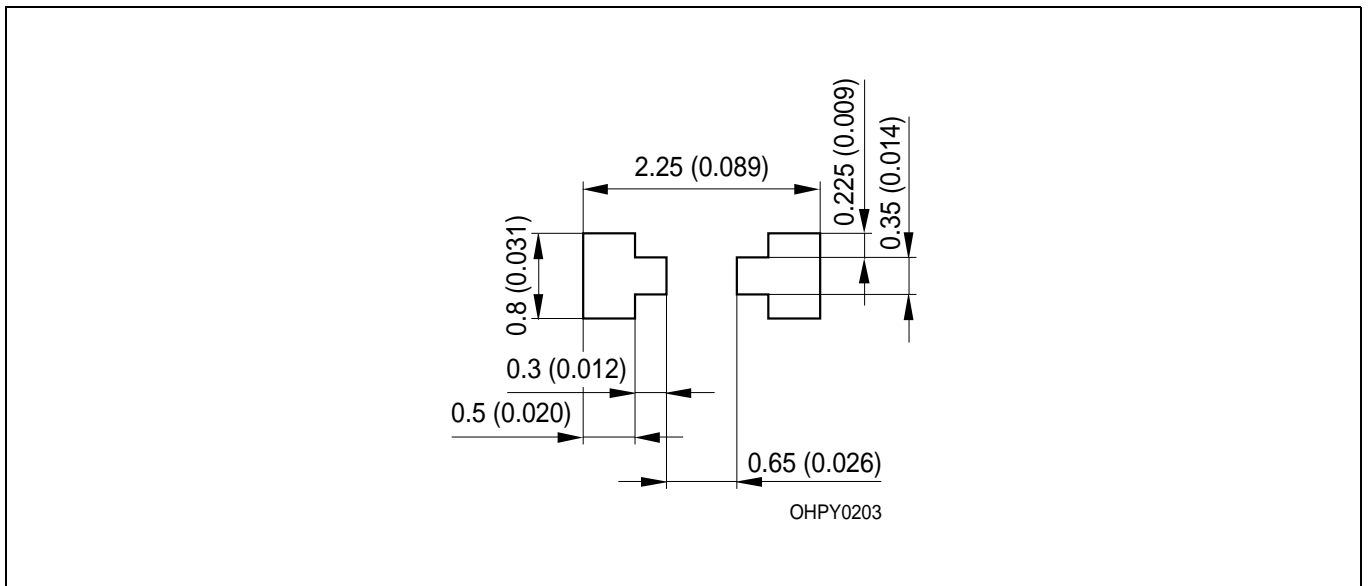
Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Empfohlenes Lötpad design verwendbar für CHIPLED und Chiplid - Bauform 0603

IR Reflow Löten

Recommended Solder Pad useable for CHIPLED and Chiplid - Package 0603

IR Reflow Soldering



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

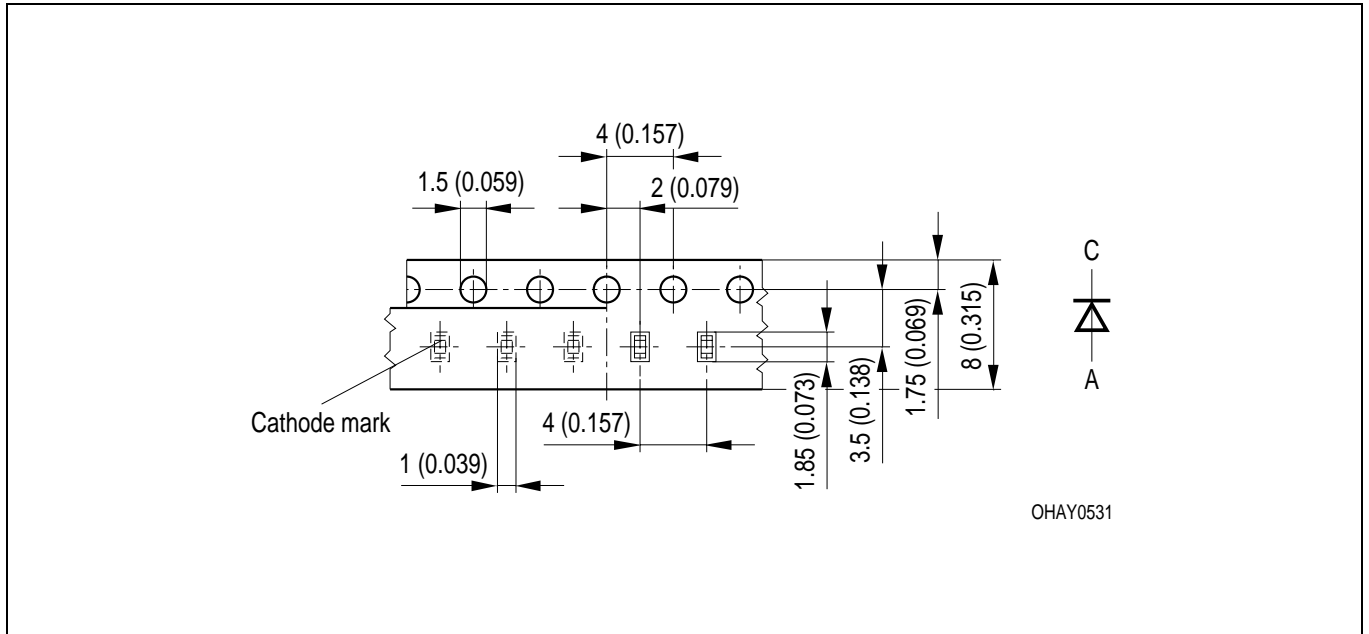
Empfohlene Lötpastendicke: 120 µm/ recommended thickness of solder paste: 120 µm

Gurtung / Polarität und Lage

Verpackungseinheit 4000/Rolle, ø180 mm

Method of Taping / Polarity and Orientation

Packing unit 4000/reel, ø180 mm



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2001-12-06

Previous Version: 2001-03-05

Page	Subjects (major changes since last revision)
9	recommended solder pad

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